

Special Issue

Trends and Applications of High-Performance Manufacturing Technologies

Message from the Guest Editors

With the continuous expansion of application space and continuous improvements in service performance, the demand for high-end equipment in various fields is rapidly increasing, and high-performance manufacturing dominated by product performance has become a key breakthrough and development direction. High-performance manufacturing establishes mechanism integrating design and manufacturing by uncovering the facets of key technologies such as performance modeling, computational reverse engineering, simulation optimization and performance testing. It promotes the transformation and upgrading of manufacturing modes, allowing geometric requirements to be met and providing performance assurance, which is of great significance for enhancing the independent innovation and manufacturing capabilities of high-end equipment.

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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